

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

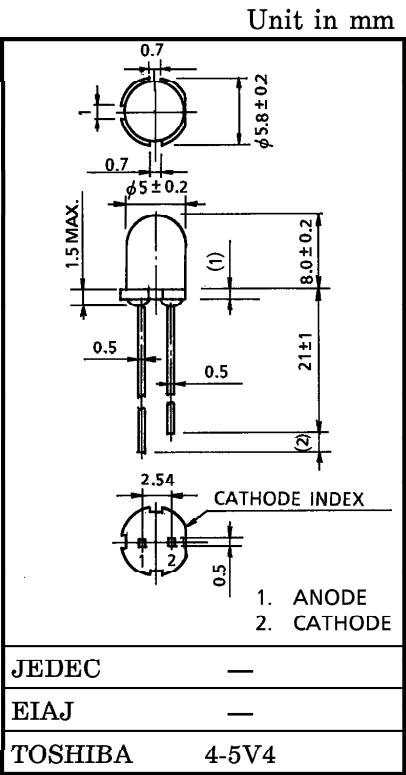
TLGD135AP

PANEL CIRCUIT INDICATOR

- All Plastic Mold Type  
Clear Transparent Lens
- High Intensity & Moderate Radiation Angle  
Half Angle = ±15 deg. (Typ.) (limits for 50% of I<sub>V</sub>)  
Recommended Forward Current : I<sub>F</sub> = 15~20mA (DC)
- Fast Response Time, Capable of Pulse Operation.
- Without stand-offs

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I <sub>F</sub>	40	mA
Reverse Voltage	V <sub>R</sub>	4	V
Power Dissipation	P <sub>D</sub>	120	mW
Operating Temperature Range	T <sub>opr</sub>	-20~85	°C
Storage Temperature Range	T <sub>stg</sub>	-30~100	°C



Weight : 0.33g

ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20mA	—	2.15	2.8	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 4V	—	—	5	μA
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20mA (Note)	153	300	—	mcd
			153	—	736	
Peak Emission Wave Length	λ <sub>p</sub>	I <sub>F</sub> = 20mA	—	567	—	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> = 20mA	—	25	—	nm

(Note) Rank selection carried out under next standard range respectively, although it needs ±15% sdditionary for guaranteed limits.

P : 180-360mcd    Q : 320-640mcd

Each rank products is classified by package unit, and (PQ) includes P and Q.

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**PRECAUTION**

Please be careful of the followings.

- Soldering temperature : 260°C MAX.      Soldering time : 3s MAX.  
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

